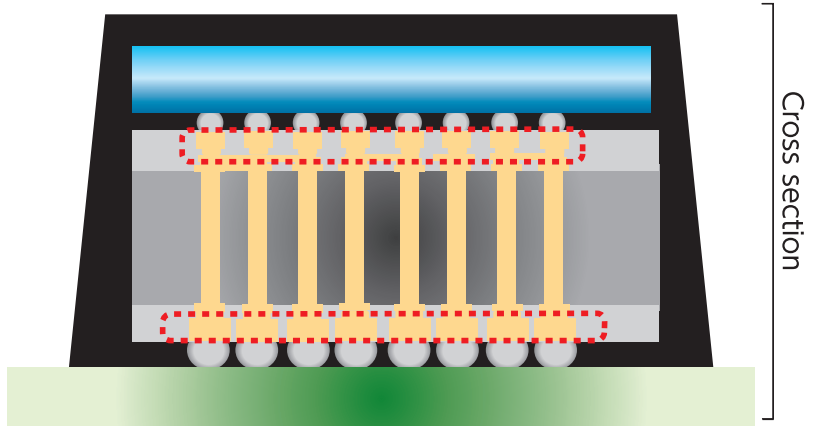
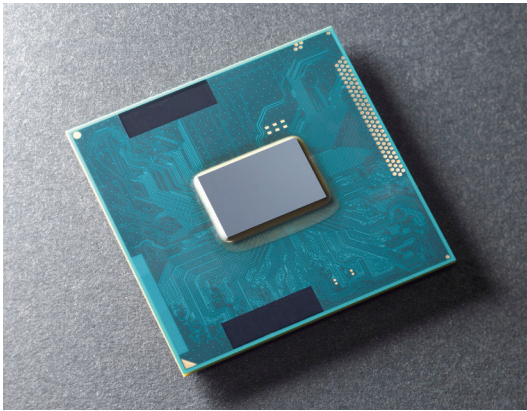


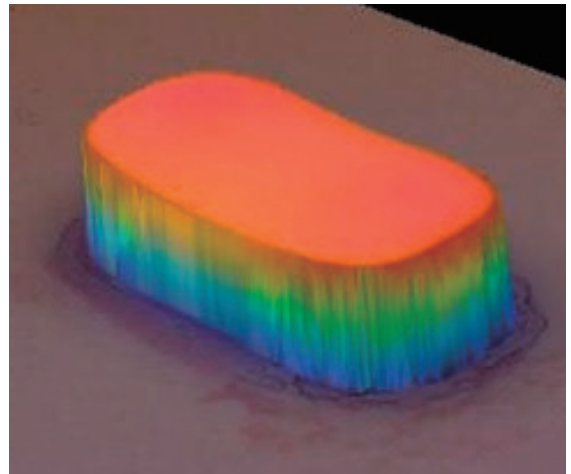
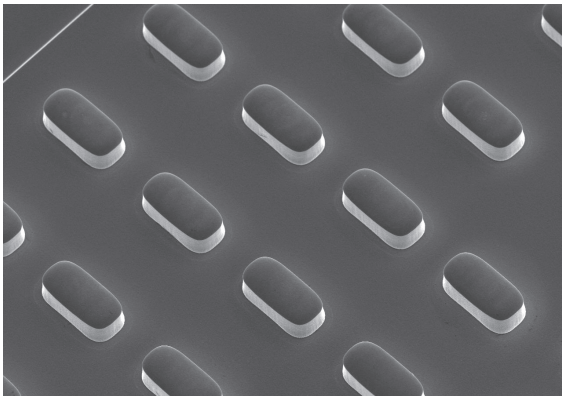
Acid copper plating additive to FO-PLP/WLP for high current density, copper bump formation

# TORYZA LCN SP



## Uniform height of bump

## Flat surface formation



Current density: 5 A/dm<sup>2</sup>  
 Pillar height: 30 μm  
 Wafer size: 6 inch

## Uniform surface thickness

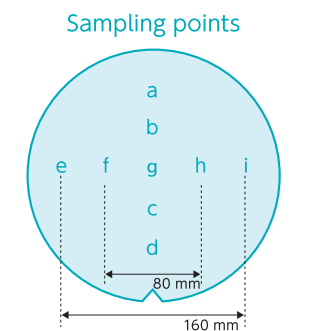
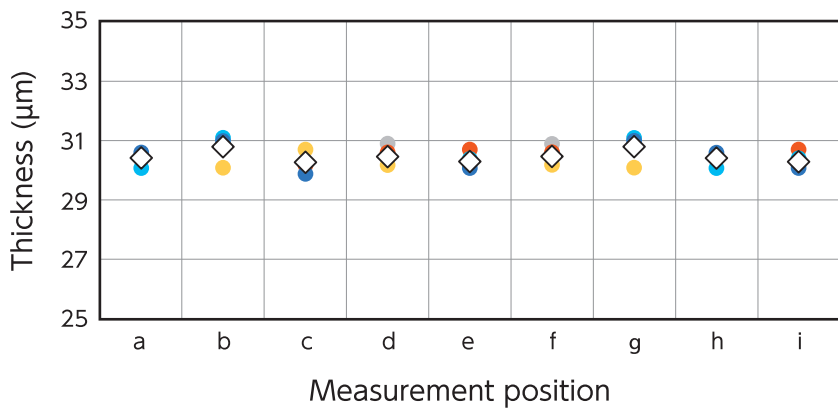


Image of wafer and measurement position